T-46-13-29



Am27C64

8,192 x 8-Bit CMOS EPROM

Advanced Micro Devices

DISTINCTIVE CHARACTERISTICS

- Fast access time-55 ns
- Low power consumption: -100 µA maximum standby current
- Programming voltage: 12.75 V
- Single +5 -V power supply

- JEDEC-approved pinout
- ±10% power supply tolerance
- Fast Flashrite™ programming
- Latch-up protected to 100 mA from -1 V to Vcc +1 V

GENERAL DESCRIPTION

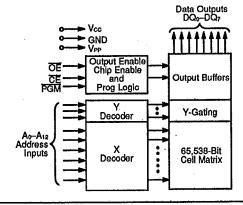
The Am27C64 is a 64K-bit, ultraviolet erasable programmable read-only memory. It is organized as 8,192 words by 8 bits per word, operates from a single +5-V supply, has a static standby mode, and features fast single address location programming. Products are available in windowed ceramic DIP and LCC packages, as well as plastic one-time programmable (OTP) packages.

Typically, any byte can be accessed in less than 55 ns. allowing operation with high-performance microprocessors without any WAIT states. The Am27C64 offers separate Output Enable (OE) and Chip Enable (CE) controls, thus eliminating bus contention in a multiple bus microprocessor system.

AMD's CMOS process technology provides high speed, low power, and high noise immunity. Typical power consumption is only 100 mW in active mode, and 250 µW in standby mode.

All signals are TTL levels, including programming signals. Bit locations may be programmed singly, in blocks, or at random.

BLOCK DIAGRAM



11419-001A

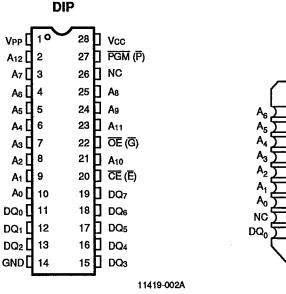
PRODUCT SELECTOR GUIDE

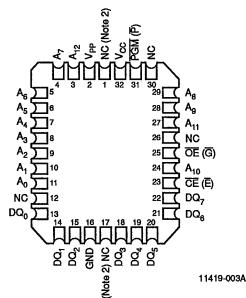
Family Part No.				Am270	C64		
Ordering Part Number ±5% Vcc Tolerance	-55	–75					-255
±10% Vcc Tolerance	_	70	90	120	150	-200	-250
Max. Access Time (ns)	55	70	90	120	150	200	250
CE (E) Access (ns)	55	70	90	120	150	200	250
OE (G) Access (ns)	35	40	40	50	65	75	100

Publication# 11419 Rev. B Amendment/0 issue Date: March 1991

CONNECTION DIAGRAMS Top View

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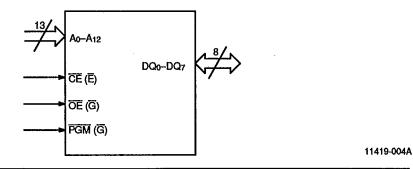
LCC*

Also Available in a 32-pin rectangular plastic leaded chip carrier

Notes:

- JEDEC nomenclature is in parantheses. Don't use (DU) for PLCC.

LOGIC SYMBOL



PIN DESCRIPTION

Ao - A12 Address Inputs

CE (E) Chip Enable Input

 $DQ_0 - DQ_7 =$ Data inputs/Outputs

OE (G) **Output Enable Input**

PGM (P) Program Enable Input Vcc Vcc Supply Voltage

Vpp **Program Supply Voltage**

GND Ground

No Internal Connection NC

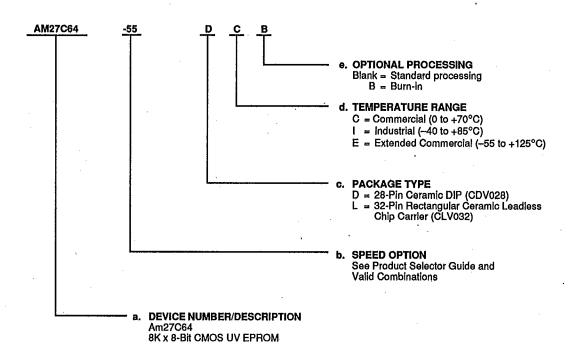
DU = No External Connection

ORDERING INFORMATION Standard Products

T-46-13-29

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:

a. Device Number
b. Speed Option
c. Package Type
d. Temperature Range
e. Optional Processing



Valid Con	nbinations
AM27C64-55	DC, DCB,
AM27C64-70	DI, DIB, LC,
AM27C64-75	LCB, LI, LIB
AM27C64-90	DC, DCB, DI,
AM27C64-120	DIB, DE, DEB,
AM27C64-150	LC, LCB, LI, LIB, LE, LEB,
AM27C64-200	
AM27C64-255	

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the lo-cal AMD sales office to confirm availability of specific valid combinations or to check on newly released combinations.

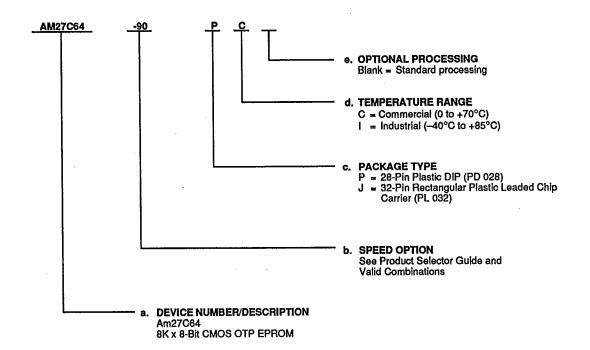
ORDERING INFORMATION OTP Products

T-46-13-29

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:

a. Device Number

- b.
- Speed Option
 Package Type
 Temperature Range
 Optional Processing c. d.



Valid Combinations						
AM27C64-90	JC, PC					
AM27C64-120						
AM27C64-150	JC, PC,					
AM27C64-200	JI, Pl					
AM27C64-255						

Valid Combinations

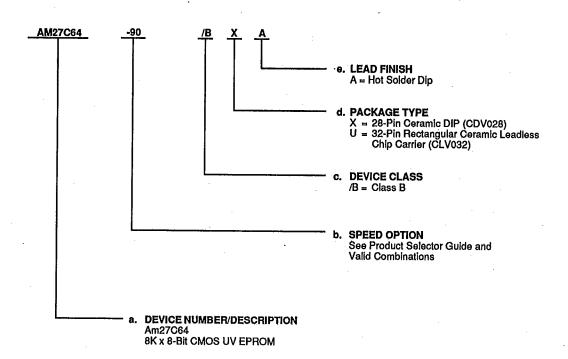
Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations or to check on newly released combinations.

MILITARY ORDERING INFORMATION APL Products

T-46-13-29

AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883C requirements. The order number (Valid Combination) is formed by a combination of:

a. Device Number
b. Speed Option
c. Package Type
d. Temperature Hange
e. Lead Finish



Valid Combinations							
AM27C64-90							
AM27C64-120	1 .						
AM27C64-150	/BXA, /BUA						
AM27C64-200	1						
AM27C64-250							

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Con-sult the local AMD sales office to confirm availability of specific valid combinations, or to check on newly released combinations.

Group A Tests

Group A tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, 11.

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FUNCTIONAL DESCRIPTION Erasing the Am27C64

In order to clear all locations of their programmed contents, it is necessary to expose the Am27C64 to an ultraviolet light source. A dosage of 15 W seconds/cm2 is required to completely erase an Am27C64. This dosage can be obtained by exposure to an ultraviolet lampwavelength of 2537 Angstroms (A)-with intensity of 12,000 µW/cm2 for 15 to 20 minutes. The Am27C64 should be directly under and about one inch from the source and all filters should be removed from the UV light source prior to erasure.

It is important to note that the Am27C64, and similar devices, will erase with light sources having wavelengths shorter than 4000 A. Although erasure times will be much longer than with UV sources at 2537 A, nevertheless the exposure to fluorescent light and sunlight will eventually erase the Am27C64 and exposure to them should be prevented to realize maximum system reliability. If used in such an environment, the package window should be covered by an opaque label or substance.

Programming the Am27C64

Upon delivery, or after each erasure, the Am27C64 has all 65,336 bits in the "ONE", or HIGH state. "ZEROs" are loaded into the Am27C64 through the procedure of programming.

The programming mode is entered when $12.75 \pm 0.25 \text{ V}$ is applied to the VPP pin, CE is at VIL, and PGM is at VIL.

For programming, the data to be programmed is applied 8 bits in parallel to the data output pins.

The Flashrite programming algorithm (shown in Figure 1) reduces programming time by using initial 100 µs pulses followed by a byte verification to determine whether the byte has been successfully programmed. If the data does not verify, an additional pulse is applied for a maximum of 25 pulses. This process is repeated while sequencing through each address of the EPROM.

The Flashrite programming algorithm programs and verifies at Vcc = 6.25 V and Vpp = 12.75 V. After the final address is completed, all bytes are compared to the original data with Vcc = Vpp = 5.25 V.

Program Inhibit

Programming of multiple Am27C64s in parallel with different data is also easily accomplished. Except for CE, all like inputs of the parallel Am27C64 may be common. A TTL low-level program pulse applied to an Am27C64 PGM input with VPP = 12.75 ± 0.25 and CE LOW will program that Am27C64. A high-level CE input inhibits the other Am27C64s from being programmed.

Program Verify

A verify should be performed on the programmed bits to determine that they were correctly programmed. The verify should be performed with OE and CE at VIL. PGM at Vih. and Vpp between 12.5 V and 13.0 V.

Auto Select Mode

The auto select mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment for the purpose of automatically matching the device to be programmeed with its corresponding programming algorithm. This mode is functional in the $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ ambient temperature range that is required when programming the Am27C64.

To activate this mode, the programming equipment must force 12.0 ± 0.5 V on address line A9 of the Am27C64. Two identifier bytes may then be sequenced from the device outputs by toggling address line Ao from Vil to ViH. All other address lines must be held at Vii during auto select mode.

Byte 0 ($A_0 = V_{IL}$) represents the manufacturer code, and byte 1 (Ao = VIH), the device identifier code. For the Am27C64, these two identifier bytes are given in the Mode Select table. All identifiers for manufacturer and device codes will possess odd parity, with the MSB (DQ₇) defined as the parity bit.

Read Mode

The Am27C64 has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip Énable (CE) is the power control and should be used for device selection. Output Enable (OE) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (tacc) is equal to the delay from CE to output (tce). Data is available at the outputs tOE after the falling edge of OE, assuming that CE has been LOW and addresses have been stable for at least tACC-toE.

Standby Mode

The Am27C64 has a CMOS standby mode which reduces the maximum Vcc current to 100 µA. It is placed in CMOS-standby when \overline{CE} is at $Vcc \pm 0.3$ V. The Am27C64 also has a TTL-standby mode which reduces the maximum Vcc current to 1.0 mA. It is placed in TTLstandby when CE is at VIH. When in standby mode, the outputs are in a high-impedance state, independent of the OE input.

Output OR-Tieing

To accomodate multiple memory connections, a twoline control function is provided to allow for:

- 1. Low memory power dissipation, and
- 2. Assurance that output bus contention will not occur.

It is recommended that \overline{CE} be decoded and used as the primary device-selecting function, while \overline{OE} be made a common connection to all devices in the array and connected to the READ line from the system control bus. This assures that all deselected memory devices are in their low-power standby mode and that the output pins are only active when data is desired from a particular

System Applications

memory device.

During the switch between active and standby conditions, transient current peaks are produced on the rising

and falling edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. At a minimum, a 0.1 μF ceramic capacitor (high frequency, low inherent inductance) should be used on each device between Vcc and GND to minimize transient effects. In addition, to overcome the voltage drop caused by the inductive effects of the printed circuit board traces on EPROM arrays, a 4.7 μF bulk electrolytic capacitor should be used between Vcc and GND for each eight devices. The location of the capacitor should be close to where the power supply is connected to the array.

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Mode Select Table

Mode	Pins	CE	ŌĒ	PGM	AO	Α9	Vpp	Outputs
Read		VIL	VIL	X	Х	Х	Vcc	Dout
Output D	isable	VIL	VIH	Х	X	X	Vcc	High Z
Standby	(TTL)	ViH	Χ	. X	Х	X	Vcc	High Z
Standby	(CMOS)	Vcc ± 0.3 V	Х	Х	Х	Х	Vcc	High Z
Program		VıL	Х	ViL	Х	Х	Vpp	DiN
Program	Verify	. VIL	VIL	ViH	X	Х	Vpp	Douт
Program	Inhibit	ViH	Х	X	Х	Х	VPP	High Z
Auto Select	Manufacturer Code	VIL	VIL	Х	, VIL	Vн	Vcc	01H
(Note 3)	Device Code	VIL	VIL	Х	ViH	VH	Vcc	15H

- 1. X can be either VIL or VIH
- 2. $VH = 12.0 V \pm 0.5 V$
- 3. $A_1-A_8 = A_{10}-A_{12} = V_{1L}$
- 4. See DC Programming Characteristics for VPP voltage during programming.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature:

OTP Products All Other Products

-65 to + 125°C -65 to + 150°C

Ambient Temperature with Power Applied

-55 to +125°C

Voltage with Respect to Ground: All pins except A₉, V_{PP}, and

Vcc (Note 1)

-0.6 to Vcc + 0.6 V

A9 and VPP (Note 2)

-0.6 to 13.5 V -0.6 to 7.0 V

Vcc

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure of the device to absolute maximum rating conditions for ex-tended periods may affect device reliability.

Notes:

- 1. During transitions the inputs may overshoot GND to -2.0 V for periods of up to 20 ns. Maximum DC voltage on input and I/O may overshoot to Vcc + 2.0 V for periods up to 20 ns.
- 2. During transitions, As and VPP may overshoot GND to -2.0 V for periods of up to 20 ns. Ag and VPP must not exceed 13.5 V for any period of time.

OPERATING RANGES

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Commercial (C) Devices

Case Temperature (Tc)

0 to +70°C

industrial (I) Devices

Case Temperature (Tc)

-40 to +85°C

Extended Commercial (E) Devices

Case Temperature (Tc)

-55 to +125°C

Military (M) Devices

Case Temperature (Tc)

-55 to +125°C

Supply Read Voltages:

Vcc/Vpp for Am27C64-XX5

+4.75 to +5.25 V

Vcc/Vpp for Am27C64-XX0 +4.50 to +5.50 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over operating range unless otherwise specified (Notes 1, 4, 5 & 8)

TTL and NMOS Inputs

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit	
Vон	Output HIGH Voltage	Iон = -400 mA		2.4		٧
Vol	Output LOW Voltage	loL = 2.1 mA			0.45	٧
ViH	Input HIGH Voltage			2.0	Vcc + 0.5	٧
ViL	Input LOW Voltage			-0.5	+0.8	٧
lu	Input Load Current	Vin = 0 V to Vcc	C/I Devices E/M Devices		1.0 5.0	μA
lLO	Output Leakage Current	Vour = 0 V to Vcc	C/I Devices E/M Devices		10 10	μА
lcc ₁	Vcc Active Current (Note 5)	CE = VIL, C/I Devices f = 5 MHz.			30	mA
		lout = 0 mA (Open Outputs)	E/M Devices		30	
lcc2	Vcc Standby Current	CE = VIH, OE = VIL	C/I Devices E/M Devices		1.0	mA
IPP1	V _{PP} Supply Current (Read) (Note 6)	CE = OE = V _{IL} , V _{PP} = V _{CC}			100	μА

DC CHARACTERISTICS over operating range unless otherwise specified (Continued) CMOS Innute T_/16_13_20

MOS INP	,				1-46-1	3-29
Parameter Symbol	Parameter Description	Test Conditions		Min.	Max.	Unit
Vон	Output HIGH Voltage	Іон =400 µA		2.4		V
Vol	Output LOW Voltage	loL = 2.1 mA			0.45	٧
ViH	Input HIGH Voltage	·		Vcc - 0.3	Vcc + 0.3	· V
VIL	Input LOW Voltage			0.5	+0.8	٧
łu .	Input Load Current	Vin = 0 V to Vcc	C/I Devices E/M Devices		1.0 5.0	μΑ
lLO	Output Leakage Current	Vout = 0 V to Vcc	C/I Devices E/M Devices		10 10	μА
lcc1	Vcc Active Current (Note 5)	CE = VIL, f = 5 MHz,	C/I Devices		25	mA
· ·	,	louт = 0 mA (Open Outputs)	E/M Devices		25	
lcc2	Vcc Standby Current	CE = Vcc ± 0.3 V C/I Devices E/M Devices			100 120	μА
lpp ₁	V _{PP} Supply Current (Read) (Note 6)	CE = OE = VIL, VPP		100	μΑ	

CAPACITANCE (Notes 2, 3, & 7)

Parameter Symbol	Parameter Description	Test Conditions	Тур.	Max.	Unit
C _{IN1}	Address Input Capacitance	VIN = 0 V	8	12	pF
C _{IN2}	OE Input Capacitance	VIN = 0 V	8	12	pF
CIN3	CE Input Capacitance	VIN = 0 V	9	12	pF
Соит	Output Capacitance	Vout = 0 V	8	12	pF

- 1. Vcc must be applied simultaneously or before Vpp, and removed simultaneously or after Vpp.
- 2. Typical values are for nominal supply voltages.
- 3. This parameter is only sampled and not 100% tested.
- 4. Caution: The Am27C64 must not be removed from, or inserted into, a socket or board when Vpp or Vcc is applied.
- 5. Icc1 is tested with $\overline{OE} = V_{IH}$ to simulate open outputs.
- 6. Maximum active power usage is the sum of Icc and IPP.
- 7. $TA = 25^{\circ}C$, f = 1 MHz.
- 8. During transitions, the inputs may overshoot to -2.0 V for periods less than 20 ns. Maximum DC voltage on input pins may overshoot to Vcc + 2.0 V for periods less than 20 ns.

SWITCHING CHARACTERISTICS over operating ranges unless otherwise specified (Notes 1, 3, & 4) T-46-13-29

Para	meter						4m27C	64			i	
Sym JEDEC	bols Standard	Parameter Description	Test Condition	ons	-55	-70, -75	-90	-120	-150	-200	-255 -250	Unit
tavqv	tacc	Address to Output Delay	CE = OE = VIL	Min. Max.	55	70	90	120	150	200	250	ns
telav	t CE	Chip Enable to Output Delay	OE = V _{IL}	Min. Max.	55	70	90	120	150	200	250	ns
tglav	toe	Output Enable to Output Delay	CE = VIL	Min. Max.	35	40	40	50	65	75	100	ns
tенzа, tанаz	tor	Output Enable HIGH to Output Float (Note 2)		Min. Max.	25	25	25	30	30	30	30	ns
taxox	tон	Output Hold from Addresses, CE, or OE,		Min.	0	0	0	0	0	0	0	ns
		whichever occurred first		Мах.								

Notes:

- 1. Vcc must be applied simultaneously or before Vpp, and removed simultaneously or after Vpp.
- 2. This parameter is only sampled and not 100% tested.
- 3. Caution: The Am27C64 must not be removed from, or inserted into, a socket or board when VPP or Vcc is applied.
- 4. For the -55, -70, and -75:

Output Load: 1 TTL gate and CL = 30 pF.

Input Rise and Fall Times: 20 ns,

Input Pulse Levels: 0 to 3 V,

Timing Measurement Reference Level: 1.5 V for inputs and outputs.

For all other versions:

Output Load: 1 TTL gate and CL = 100 pF,

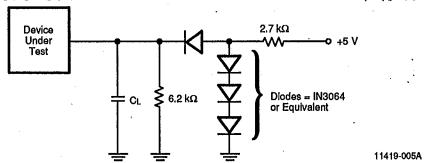
Input Rise and Fall Times: 20 ns,

Input Pulse Levels: 0.45 to 2.4 V,

Timing Measurement Reference Level: 0.8 V and 2 V for inputs and outputs.

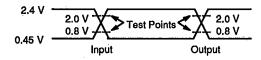
SWITCHING TEST CIRCUIT

T-46-13-29

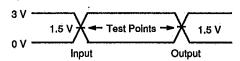


CL = 100 pF including jig capacitance (30 pF for -55, -70, and -75)

SWITCHING TEST WAVEFORMS



AC Testing: Inputs are driven at 2.4 V for a logic "1" and 0.45 V for a logic "0". Input pulse rise and fall times are ≤ 20 ns.

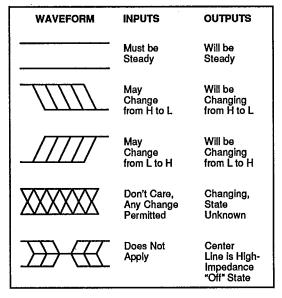


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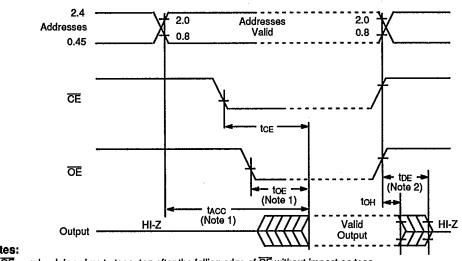
AC Testing: Inputs are driven at 3.0 V for a logic "1" and 0 V for a logic "0". Input pulse rise and fall times are ≤ 20 ns for -55, -70, and -75 devices.

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SWITCHING WAVEFORMS Key to Switching Waveforms



KS000010



Notes:

OE may be delayed up to tacc—toe after the falling edge of CE without impact on tacc.
 toe is specified from OE or CE, whichever occurs first.

11419-007A

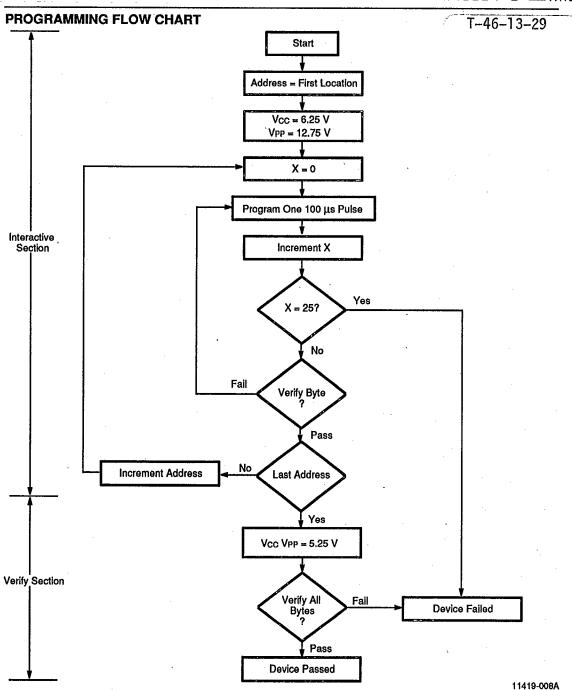


Figure 1. Flashrite Programming Flow Chart

DC PROGRAMMING CHARACTERISTICS ($T_A = +25^{\circ}\text{C} \pm 5^{\circ}\text{C}$) (Notes 1, 2, & 3) T-46-13-29

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit
lu	Input Current (All Inputs)	Vin = Vil of Vih		10.0	μΑ
VıL	Input LOW Level (All Inputs)		-0.3	8.0	٧
Virt	Input HIGH Level		2.0	Vcc + 0.5	٧
Vol	Output LOW Voltage During Verify	loL = 2.1 mA		0.45	٧
Vон	Output HIGH Voltage During Verify	іон = −400 μА	2.4		٧
Vн	As Auto Select Voltage		11.5	12.5	٧
lccз	Vcc Supply Current (Program & Verify)			50	mA
lpp2	VPP Supply Current (Program)	CE = VIL, OE = VIH		30	mA
Vcc	Flashrite Supply Voltage		6.00	6.50	V
VPP	Flashrite Programming Voltage		12.5	13.0	٧

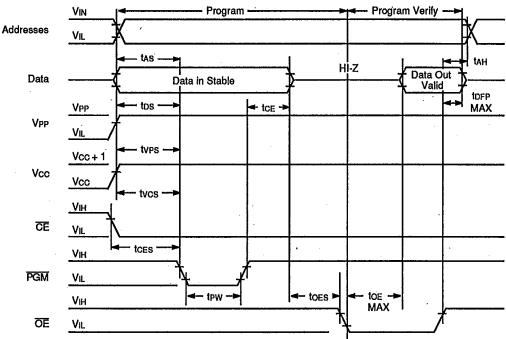
SWITCHING PROGRAMMING CHARACTERISTICS (T_A = +25°C ±5°C) (Notes 1, 2, & 3)

Parameter	Symbols	Parameter			
JEDEC	Standard	Description	Min.	Max.	Unit
tavel	tas	Address Setup Time	2		μs
tozaL	toes	OE Setup Time	2		μs
telpl	tces	CE Setup Time	2		μs
tovel	tos	Data Setup Time	2		με
tghax	tah	Address Hold Time	0		μs
tehox	toн	Data Hold Time	2		μs
tаноz	torp	Output Enable to Output Float Delay	0	100	ns
tvps	tvps	V _{PP} Setup Time	2		μs
t ELEH1	tpw	PGM Program Pulse Width	95	105	μs
tvcs	tycs	Vcc Setup Time	2		μs
tglav	toe	Data Valid from OE		100	ns

- 1. Vcc must be applied simultaneously or before Vpp, and removed simultaneously or after Vpp.
- 2. When programming the Am27C64, a 0.1 μ F capacitor is required across VPP and ground to suppress spurious voltage transients which may damage the device.
- 3. Programming characteristics are sampled but not 100% tested at worst-case conditions.

PROGRAMMING ALGORITHM WAVEFORMS (Notes 1 & 2)

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- 1. The input timing reference level is 0.8 V for VIL and 2 V for VIH.
- 2. toe and topp are characteristics of the device, but must be accommodated by the programmer.